# 2SC2188

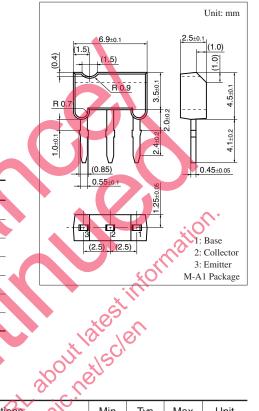
# Silicon NPN epitaxial planar type

For intermediate frequency amplification of TV image

#### Features

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- High transition frequency  $f_T$
- $\bullet$  Satisfactory linearity of forward current transfer ratio  $h_{FE}$
- M type package allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board



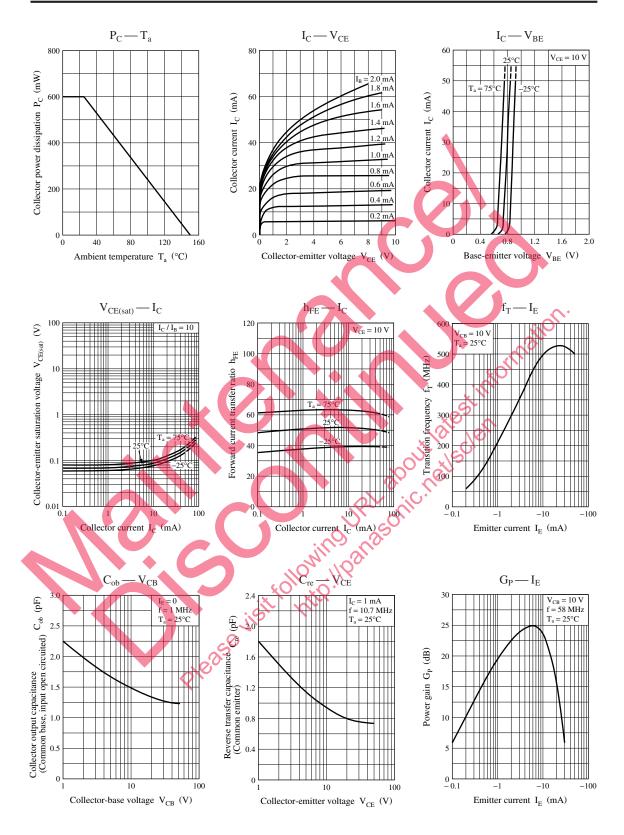
## Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	45	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	35	V	
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	4	V	
Collector current	I <sub>C</sub>	50	mA	
Collector power dissipation	PC	600	mW	
Junction temperature	Tj	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

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Parameter	Symbol		Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$l_{\rm C} = 10 \ \mu$	A, $I_E = 0$	45			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 1 mA$	$I_{\rm R} = 0$	35			V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	$I_{\rm E} = 10 \mu$	$A, I_C = 0$	4			V
Collector-emitter cutoff current (Base open)	I <sub>CEO</sub>	$V_{CE} = 20$	$V, I_B \Rightarrow 0$			10	μΑ
Forward current transfer ratio	h <sub>FE</sub>	$V_{CB} = 10$	$V_{*}I_{\rm E} = -10 \text{ mA}$	20	50	100	_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_{\rm C} = 20  {\rm m}$	A, $I_B = 2 \text{ mA}$			0.5	V
Transition frequency	F	$V_{CB} = 10$	V, $I_E = -10 \text{ mA}$ , $f = 100 \text{ MHz}$	300	500		MHz
Reverse transfer capacitance	C <sub>re</sub>	$V_{CB} = 10$	V, $I_E = -1 \text{ mA}$ , $f = 10.7 \text{ MHz}$			1.5	pF
(Common emitter)							
Power gain	G <sub>P</sub>	$V_{CB} = 10$	V, $I_E = -10 \text{ mA}$ , $f = 58 \text{ MHz}$		18		dB

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.



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